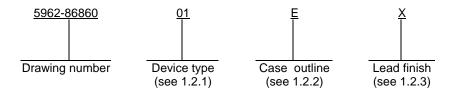
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1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
 - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	HA-4902	Precision quad comparator

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Е	GDIP1-T16 or CDIP2-T16	16	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings.

Voltage between +V and –V terminals Differential input voltage Output short-circuit duration Peak output current Storage temperature range	±15 V dc Indefinite <u>1</u> / ±50 mA
Maximum power dissipation (P _D): Case E Case 2 Lead temperature (soldering, 10 seconds)	1.32 W <u>3</u> /
Thermal resistance, junction-to-case (θ_{JC})	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ _{JA}): Case E Case 2 Junction temperature (T _J)	76°C/W

1.4 Recommended operating conditions.

Positive supply voltage (+V)	+15 V dc
Negative supply voltage (-V)	
Logic supply voltage (+V _L)	
Logic reference voltage (-V _L)	
Ambient temperature range (T _A)	-55°C to +125°C

- 1/ One amplifier shorted to ground.
- 2/ Derate linearly above $T_A = +75$ °C at 13.4 mW/°C.
- 3/ Derate linearly above $T_A = +75$ °C at 13.1 mW/°C.

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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 -- Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 -- List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

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TABLE I. Electrical performance characteristics.

Test	Symbol		Group A subgroups	Device type	Li	mits	Unit
					Min	Max	
Input offset voltage	V _{IO}	$V_{CM} = 0 \text{ V}, V_{OUT} = 1.4 \text{ V} \underline{2}/$	1	01		±5.0	mV
			2, 3			±8.0	1
Input bias current	+l _B	$V_{CM} = 0 V$	1	01		±150	nA
			2, 3			±200	
	-I _B		1			±150	
			2, 3			±200	
Input offset current	I _{IO}	$V_{CM} = 0 V$	1	01		±35	nA
			2, 3			±45	
Input sensitivity	IN _{SEN}	V _{CM} = 0 V	1	01		±0.5	mV
			2, 3			±0.6	
Output low voltage	V _{OL}	I _{SINK} = 3.0 mA	1, 2, 3	01		0.4	V
Output high voltage	V _{OH}	I _{SOURCE} = 3.0 mA	1, 2, 3	01	3.5		V
Output sink current	I _{SINK}	V _{OUT} ≤ 0.4 V	1, 2, 3	01	3.0		mA
Output source current	I _{SOURCE}	V _{OUT} ≥ 0.4 V	1, 2, 3	01	-3.0		mA
Supply current	+I _{CC}	$V_{OUT} = V_{OL}$ and V_{OH}	1, 2, 3	01		20	mA
	-I _{CC}		1			8.0	1
			2, 3			10	1
Logic current	IL	V _{OUT} = V _{OL} and V _{OH}	1	01		6.0	mA
			2, 3			8.0	
Response time 3/	t _{PD0}	100 mV input step, <u>4/</u> 10 mV overdrive,	9	01		200	ns
		$T_A = +25^{\circ}C$					
	+	-100 mV input step, <u>4</u> /	9			200	4
	t _{PD1}	-10 mV overdrive,	3			200	
		$T_A = +25^{\circ}C$					
Common mode voltage	+V _{CM}	T _A = +25°C	1	01	-15	12.4	V
range <u>3</u> /	-V _{CM}	1			-15	12.4	1

^{1/}V = 15 V, -V = -15 V, and $V_L = 0 \text{ V}$ unless otherwise specified herein.

- 3/ If not tested, shall be guaranteed to the limits specified in table I.
- 4/ Duty cycle = 50%, f = 100 Hz, inverting input is driven, and all unused inverting inputs are tied to +5.0 V. See figure 3.

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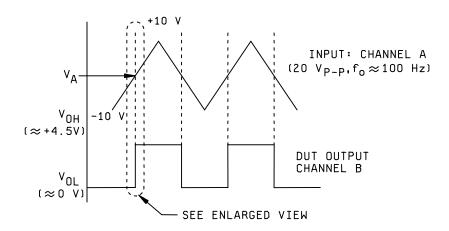
Q/ Offset voltage is measured when V_{OUT} = 1.4 V. Sensitivity is measured on the transition edge at 0.4 V and 3.5 V. Sensitivity is the change in differential input voltage required to change the output state. Sensitivity includes the effects of offset voltage and voltage gain. See figure 2.

		1
Device type	0,	1
Case outlines	E	2
Terminal number	Terminal	symbol
1	+V _L	NC
2	OUT 1	+V _L
3	-IN	OUT 1
4	+IN	-IN 1
5 6	-V	+IN 1
6	+IN 2	NC
7	-IN 2	-V
8	OUT 2	+IN 2
9	-V _L	-IN 2
10	OUT 3	OUT 2
11	-IN 3	NC
12	+IN 3	-V _L
13	+V	OUT 3
14	+IN 4	-IN 3
15	-IN 4	+IN 3
16	OUT 4	NC
17		+V
18		+IN 4
19		-IN 4
20		OUT 4

NC = No connection

FIGURE 1. <u>Terminal connections</u>.

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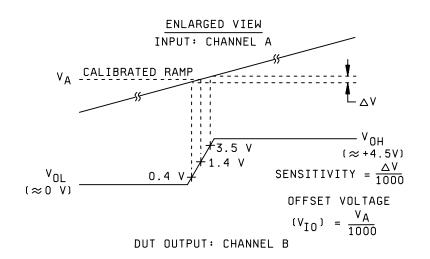
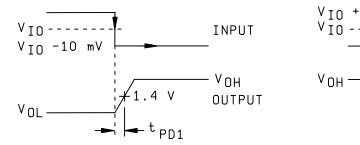
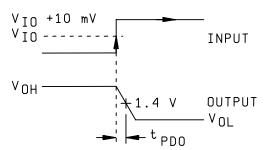


FIGURE 2. Offset voltage and sensitivity waveforms.

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NOTE: Response time testing is done after V_{IO} testing to acquire device offset voltage. Ten millivolts overdrive is then added (or subtracted depending on state) to this Measured V_{IO} value.

FIGURE 3. Response time waveforms.

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- 3.5.1 <u>Certification/compliance mark.</u> A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3
Group A test requirements (method 5005)	1, 2, 3, 9
Groups C and D end-point electrical parameters (method 5005)	1

^{*} PDA applies to subgroup 1.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, 6, 7, 8, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

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6.4 Record of users. Military and industrial users shall inform requires configuration control and the applicable SMD. DSCC will coordination and distribution of changes to the drawings. Users should contact DSCC-VA, telephone (614) 692-0544. 6.5 Comments. Comments on this drawing should be directed.	ill maintain a recor of drawings cover	rd of users and this list will l ing microelectronics device	oe used for s (FSC 5962)
(614) 692-0547.6.6 Approved sources of supply. Approved sources of supply HDBK-103 have agreed to this drawing and a certificate of comp			
by DSCC-VA.			
_	SIZE		
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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 04-01-27

Approved sources of supply for SMD 5962-86860 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-8686001EA	34371	HA1-4902/883
5962-86860012A	34371	HA4-4902/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34371

Vendor name and address

Intersil Corporation 2401 Palm Bay Blvd P.O. Box 883

Melbourne, FL 32902-0883

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.